

TECHNICAL DATA SHEET

Wafer Heating Module

Custom build · 2–12 inch · RT to 600 °C · ± 0.1 °C · flatness ≤ 10 μm (3 μm by material)



Wafer heating module — custom-built, 2–12 inch, RT to 600 °C.

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SECTION I

Product Description

The wafer heating module is a key component in semiconductor process flows — wafer annealing, bonding, photoresist coating, etching, vapor deposition, and other critical steps. It provides a stable thermal field and precise across-plate temperature uniformity so the wafer meets its heating requirement in every temperature zone, supporting semiconductor device manufacturing and R&D.

Each module is built to order: 2–12 inch sizes, RT to 600 °C with ± 0.1 °C stability, plate materials including aluminum alloy, stainless steel, and Invar alloy, and flatness of ≤ 10 μm — down to 3 μm depending on material. Modules are specified for atmosphere or vacuum, with optional cooling systems (water or gas cooling) and an optional 0–100 kN bonding force.

SECTION II

Specifications

Wafer Heating Module — Specifications	
Model #	Custom
SKU #	EIWHM001
Wafer Size	2 / 4 / 6 / 8 / 10 / 12 inch
Temperature Range	RT ~ 600 °C
Temperature Stability	± 0.1 °C
Material	Aluminum alloy, stainless steel, Invar alloy, etc.
Flatness	≤ 10 μm ; down to 3 μm , material-dependent
Operating Environment	Atmosphere / vacuum
Cooling System	Optional — water cooling, gas cooling, etc.
Bonding Force	Optional — 0 ~ 100 kN

SECTION III

Application Fields

- Wafer annealing
- Wafer bonding
- Photoresist coating support
- Etching processes
- Vapor deposition
- Semiconductor device fabrication & R&D

SECTION IV

Configuration

As a custom-built module, the OEM materials list no fixed standard configuration; the supplied configuration and options are confirmed at quotation.

The wafer heating module is supplied by quotation: request via the product page at www.acsmaterial.com with your wafer size, temperature, and process details; our engineers reply with a proposed build, pricing, and lead time.

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